

**TITLE:** PACKAGE OUTLINE, 6x6 UCSP

DOC ID # 21-0082

NEW REV: K

OLD REV: J

EFFECTIVE:

**TYPE**

883

SMD  #

PERMANENT

TEMPORARY

EXPIRES:

**ORIGINATOR**

SHIRISH SHAH

EXT: 6332

VP NAME: RICH HOOD

OTHER DOC AFFECTED: NO  YES  LIST: →

MATL. AFFECTED: NO  YES  →

USE AS IS:

REWORK:

SCRAP:

*For Maxfab Lot Traveler Changes ONLY:* Affects version number? NO  YES  IF YES, ECN the Process Revision List.

*For Data Sheet Changes ONLY:* Review Data Sheet before printing? NO  YES  IF YES, initial

**DESIGN CHANGES ONLY:**

ROOT CAUSE:

CORRECTIVE ACTION:

**REASON FOR CHANGE:** ADDED DATA FOR B36-4 PKG. CODE.

FROM:

TO:

DETAILS ADDED FOR B36-4 PKG. CODE.

DWG. NOT TO SCALE NOTE ADDED.

"PROPRIETARY INFORMATION" DELETED FROM TITLE BLOCK.

**DISTRIBUTION:**  HQ  Maxim North  Maxfab South Manufacturing Areas N/A Offshore: N/A

**Other:** J.MOIST, L.JACKSON, M.RUBENZAHL, S. SUNG, S.SCHROEDER, A.ARREOLA, A.WICHMAN, D.GOLDBAUM, E.EVANS;

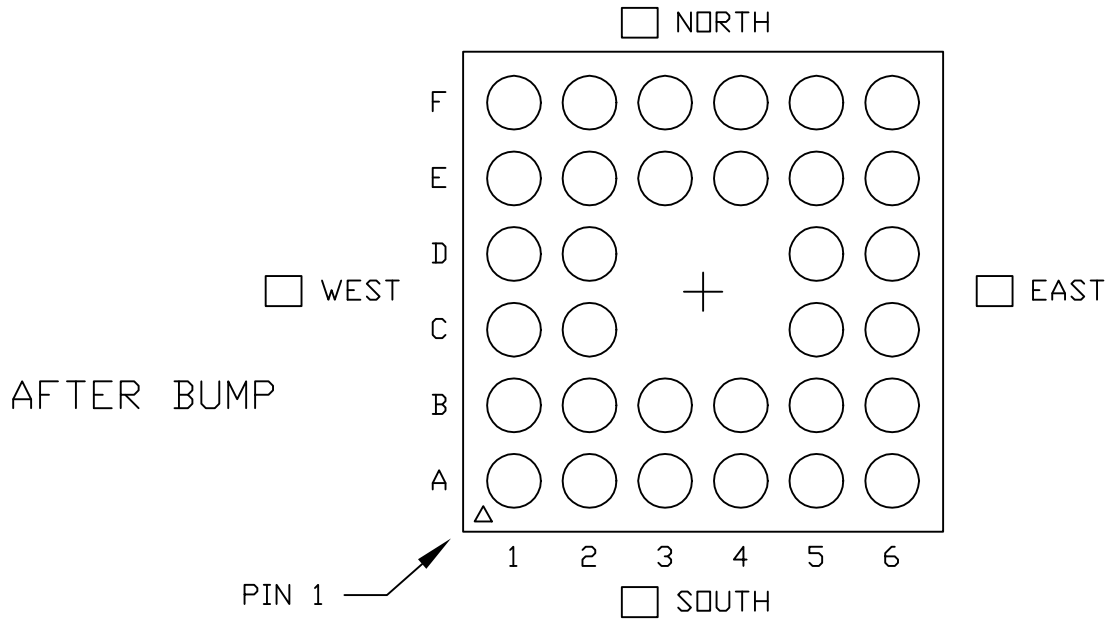
COLORADO/AUSTIN/PLANO DESIGN CENTERS

**ORIGINAL APPROVALS ARE ON FILE IN THE \_\_\_\_\_ DOCUMENT CONTROL OFFICE.**

APPROVALS	DATE	APPROVALS	DATE	APPROVALS	DATE
PKG. ENGR.	/ /	A. QUINTERO	/ /		/ /
S. CHINNUSAMY	/ /		/ /		/ /
C. KEENE	/ /		/ /		/ /

Date ECN submitted into D.C.:

Document Control processor initials:



SELECT THE BOX INDICATING THE WAFER FLAT SIDE WITH RESPECT TO PIN 1.

NOTE:  
 MAX. DIE SIZE: 125x125  
 MIN. DIE SIZE: 120x120

VIEW: BUMP SIDE UP

PKG. CODE: B36-4		SIGNATURES	DATE	<b>MAXIM</b> CONFIDENTIAL & PROPRIETARY	
CAV./PAD SIZE: N/A	PKG. DESIGN			BOND DIAGRAM #:	REV: